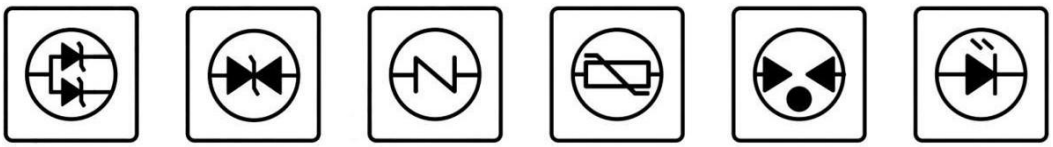
MSKSEMI 美森科
SEMICONDUCTOR



GBP2005-MS THRU GBP210-MS

Product specification

GBP2005-MS THRU GBP210-MS

VOLTAGE RANGE: 50 - 1000V
CURRENT: 2 A

FEATURES

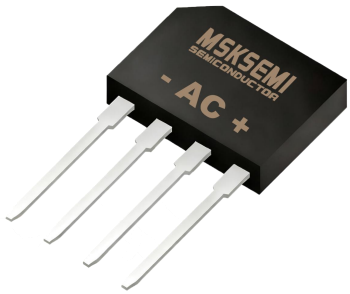
- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards

MECHANICAL DATA

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 2.0 grams (approx.)
- Mounting Position: Any
- Marking: Type Number

REFERENCE NEWS

GBP



Marking

GBP2005-MS	GBP201-MS	GBP202-MS	GBP204-MS
MSKSEMI GBP2005 + AC -	MSKSEMI GBP201 + AC -	MSKSEMI GBP202 + AC -	MSKSEMI GBP204 + AC -
GBP206-MS	**GBP208-MS**	**GBP210-MS**	
MSKSEMI GBP206 + AC -	MSKSEMI GBP208 + AC -	MSKSEMI GBP210 + AC -	

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

T_A = 25C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	GBP 2005-MS	GBP 201-MS	GBP 202-MS	GBP 204-MS	GBP 206-MS	GBP 208-MS	GBP 210-MS	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @T_A = 50°C	I_O	2.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50							A
Forward Voltage (per bridge) @I_F = 2.0A	V_{FM}	1.1							V
Peak Reverse Current @T_A = 25°C At Rated DC Blocking Voltage @T_A = 100°C	I_R	10 1.0							μA mA
Operating Temperature Range	T_j	-55 to +125							°C
Storage Temperature Range	T_{STG}	-55 to +150							°C

RATING AND CHARACTERISTIC CURVES (GBP2005-MS THRU GBP210-MS)

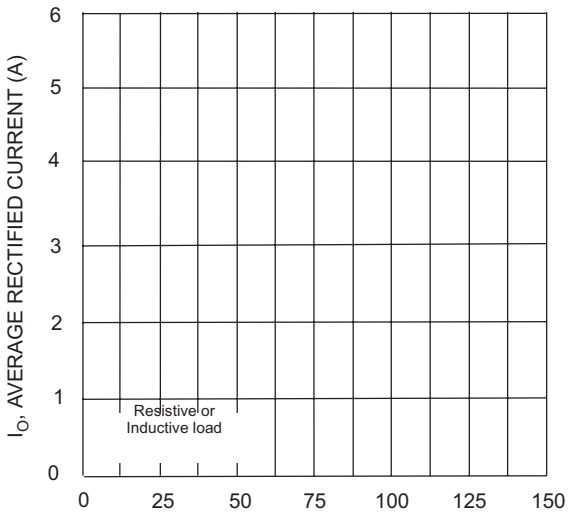


Fig. 1 Forward Current Derating Curve

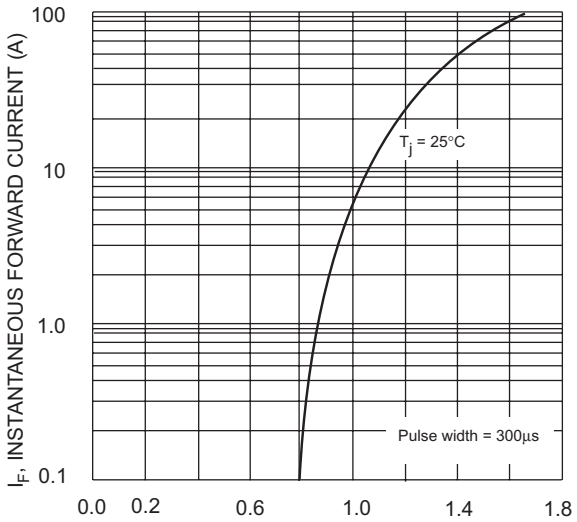


Fig. 2 Typical Fwd Characteristics, per element

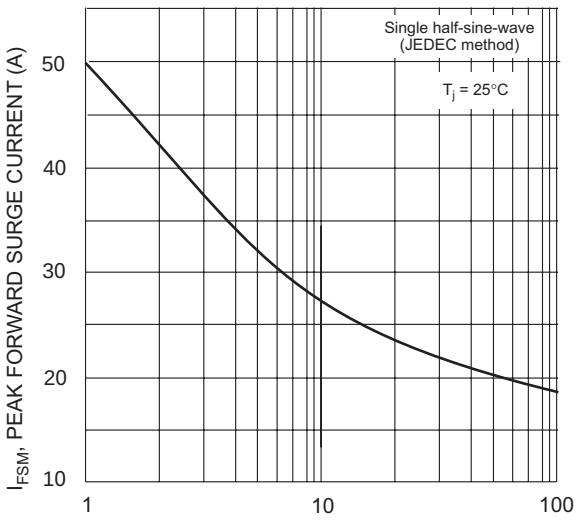


Fig. 3 Maximum Non-Repetitive Surge Current

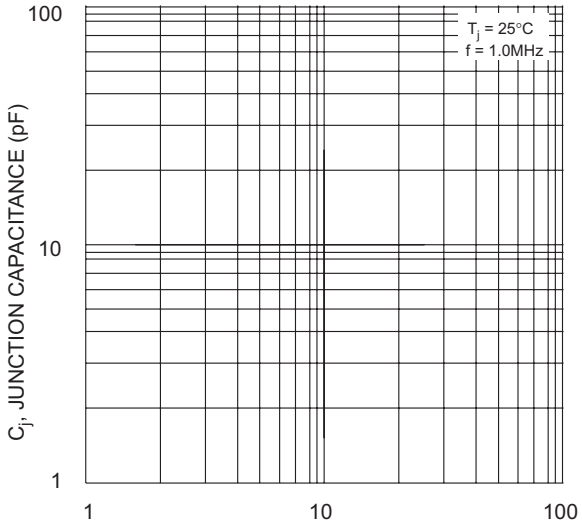
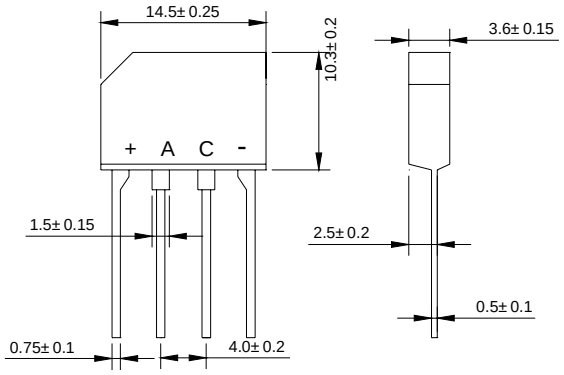


Fig. 4 Typical Junction Capacitance

PACKAGE MECHANICAL DATA

GBP



Dimensions in millimeters

REELSPECIFICATION

P/N	PKG	QTY
GBP2005-MS THRU GBP210-MS	GBP	500

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